

MA3S132DG, MA3S132EG

Silicon epitaxial planar type

For switching circuits

■ Features

- Short reverse recovery time t_{rr}
- Small terminal capacitance C_t
- Two isolated elements contained in one package, allowing high-density mounting

■ Package

- Code
SSMini3-F3
- Pin Name
MA3S132DG MA3S132EG
1: Cathode 1 1: Anode 1
2: Cathode 2 2: Anode 2
3: Anode 3: Cathode

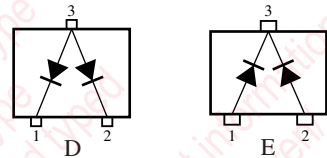
■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Reverse voltage	V_R	80	V
Maximum peak reverse voltage	V_{RM}	80	V
Forward current	Single	I_F	100
	Double		150
Peak forward current	Single	I_{FM}	225
	Double		340
Non-repetitive peak forward surge current *	Single	I_{FSM}	500
	Double		750
Junction temperature	T_j	150	$^\circ\text{C}$
Storage temperature	T_{stg}	-55 to +150	$^\circ\text{C}$

■ Marking Symbol

MA3S132DG: MO
MA3S132EG: MU

■ Internal Connection



Note) *: $t = 1 \text{ s}$

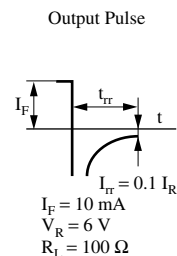
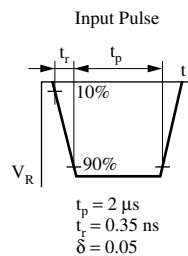
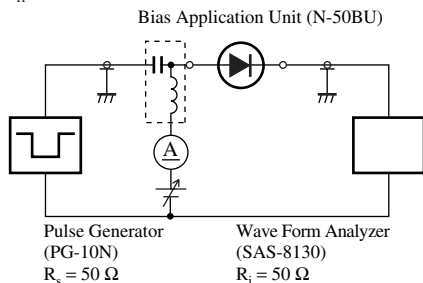
■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	V_F	$I_F = 100 \text{ mA}$			1.2	V
Reverse voltage	V_R	$I_R = 100 \mu\text{A}$	80			V
Reverse current	I_R	$V_R = 75 \text{ V}$			100	nA
Terminal capacitance	MA3S132DG	$V_R = 0 \text{ V}, f = 1 \text{ MHz}$			15	pF
	MA3S132EG				2	
Reverse recovery time *	MA3S132DG	$I_F = 10 \text{ mA}, V_R = 6 \text{ V}$ $I_{rr} = 0.1 I_R, R_L = 100 \Omega$			10	ns
	MA3S132EG				3	

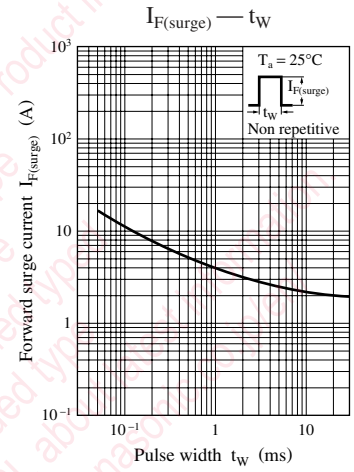
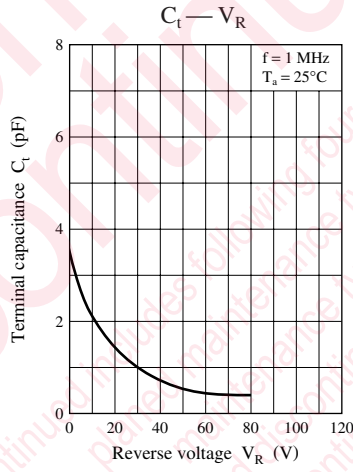
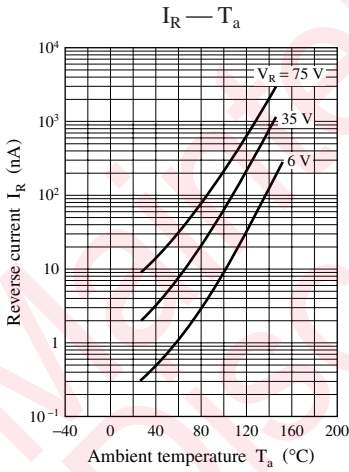
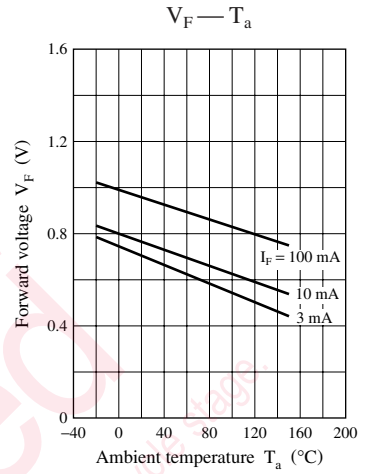
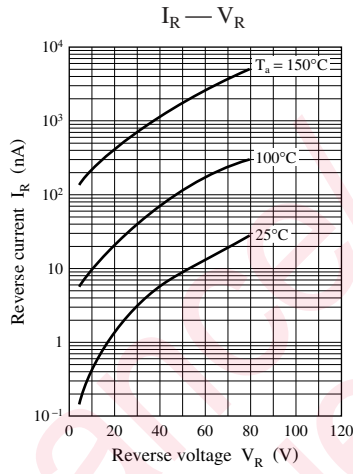
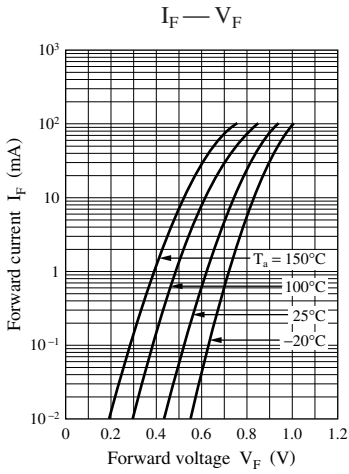
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. Absolute frequency of input and output is 100 MHz.

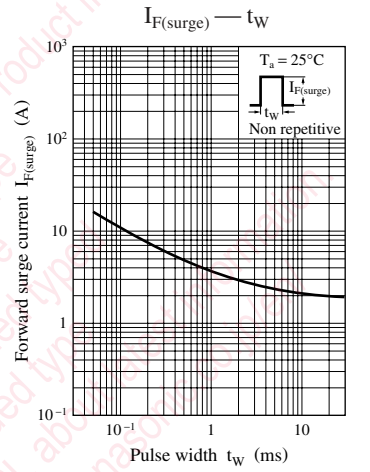
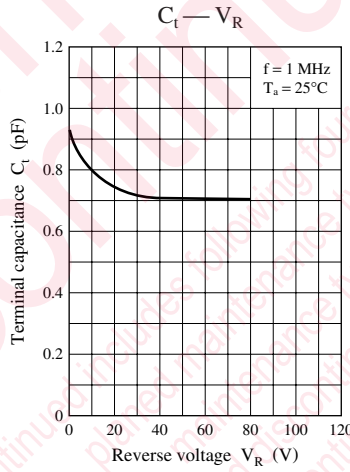
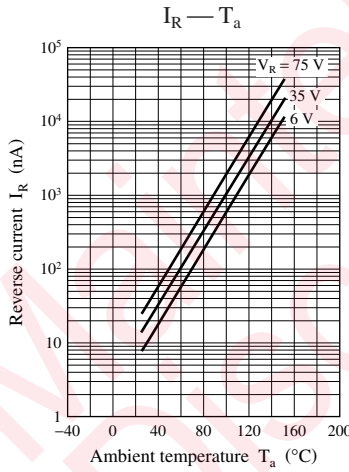
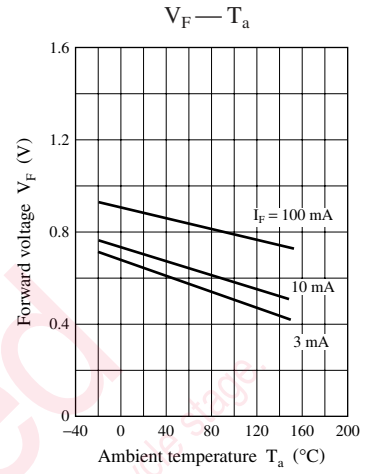
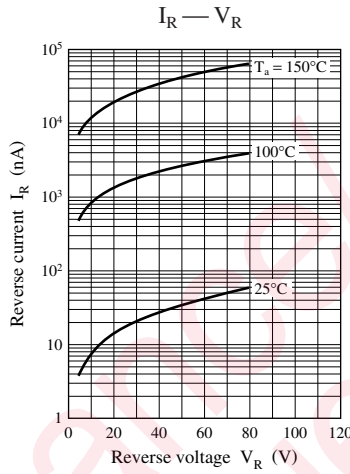
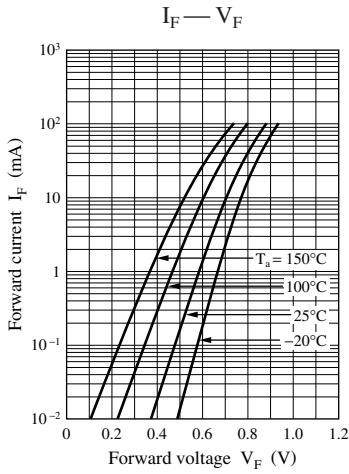
3. *: t_{rr} measurement circuit



Characteristics charts of MA3S132DG

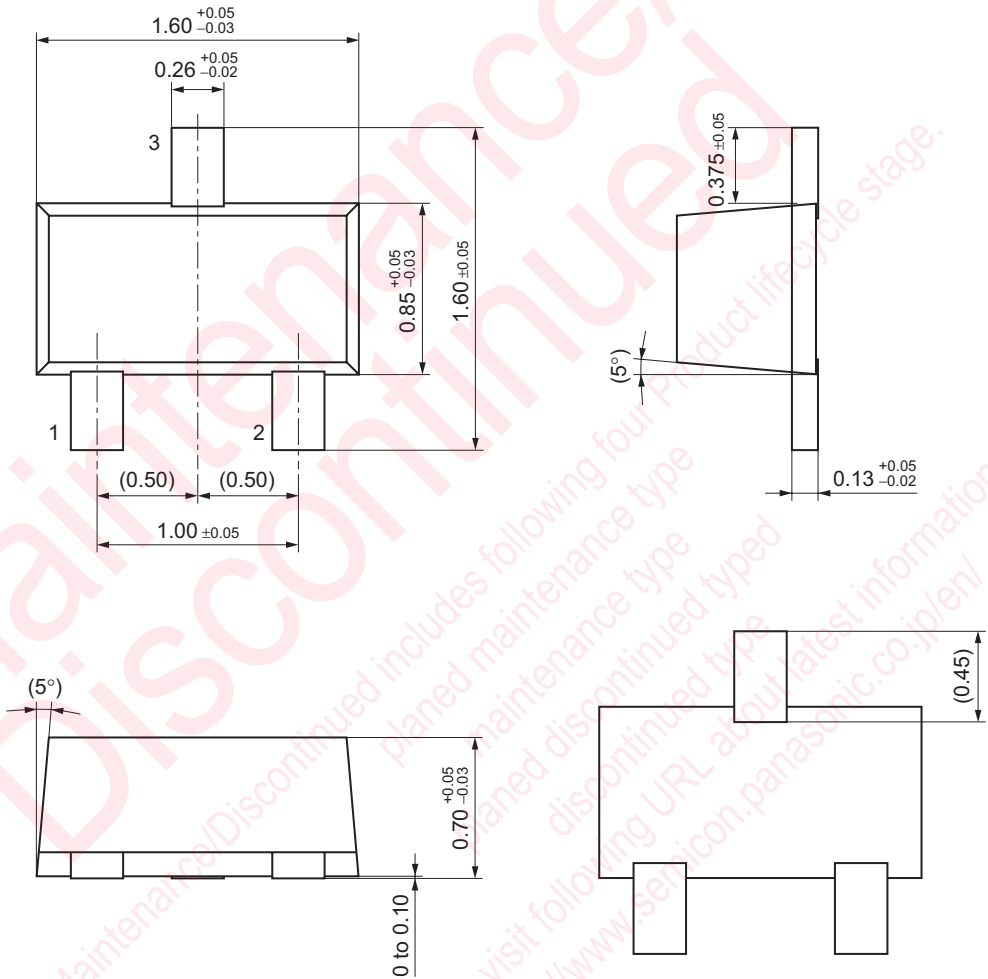


Characteristics charts of MA3S132EG



SSMini3-F3

Unit: mm



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